



L Number	Hits	Search Text	DB	Time stamp
1	62271	(etch\$3 clean\$3) and (wafer substrate) and	USPAT;	2003/07/05 15:37
		(bath container tank)	US-PGPUB	
2	3382	((etch\$3 clean\$3) and (wafer substrate)	USPAT;	2003/07/05 15:38
		and (bath container tank) ) and ((etch\$3	US-PGPUB	
		clean\$3) near10 (wafer substrate) near10		
		(bath container tank))		
4	2842	(((etch\$3 clean\$3) and (wafer substrate)	USPAT;	2003/07/05 15:38
		and (bath container tank) ) and ((etch\$3	US-PGPUB	
		clean\$3) near10 (wafer substrate) near10		
		(bath container tank))) and (liquid		
		solution)		
5	830	((((etch\$3 clean\$3) and (wafer substrate)	USPAT;	2003/07/05 15:38
		and (bath container tank) ) and ((etch\$3	US-PGPUB	
		clean\$3) near10 (wafer substrate) near10		
		(bath container tank))) and (liquid	ļ	
		solution) ) and ("HF" (hydrogn near		
	! !	fluoride) (hydro near3 fluoric near3		
_		acid))		
6	7119	(etch\$3 clean\$3) and (wafer substrate) and	EPO; JPO;	2003/07/05 15:38
		(bath container tank)	DERWENT;	
	0700		IBM_TDB	
7	2798	((etch\$3 clean\$3) and (wafer substrate)	EPO; JPO;	2003/07/05 15:38
		and (bath container tank) ) and ((etch\$3	DERWENT;	
		clean\$3) near10 (wafer substrate) near10	IBM_TDB	
0	1722	(bath container tank))		0000 (07 (05 15 00
8	1/22	(((etch\$3 clean\$3) and (wafer substrate)	EPO; JPO;	2003/07/05 15:38
		and (bath container tank) ) and ((etch\$3	DERWENT;	
		clean\$3) near10 (wafer substrate) near10	IBM_TDB	
		(bath container tank))) and (liquid solution)		
9	50	((((etch\$3 clean\$3) and (wafer substrate)	EDO. IDO.	2003/07/05 15:39
9	]	and (bath container tank) ) and ((etch\$3	EPO; JPO; DERWENT;	2003/07/05 15:39
		clean\$3) near10 (wafer substrate) near10	IBM TDB	İ
		(bath container tank))) and (liquid	I I DM_1 DB	
		solution   solution   and ("HF" (hydrogn near		
		fluoride) (hydro near3 fluoric near3		
		acid))		
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